



36V, 6A, Frequency Programmable, Step-Down Converter with Smart, Dual, USB Charging Ports

### DESCRIPTION

The MP5408 integrates a monolithic, step-down, switch-mode converter with two USB current-limit switches and charging port identification circuitry for each port. The MP5408 achieves 6A of output current with excellent load and line regulation over a wide input supply range.

The output of the USB switch is current-limited. Both USB ports support DCP schemes for battery charging specification (BC1.2), divider mode, 1.2V/1.2V mode, and USB Type-C 5V@3A DFP mode, eliminating the need for outside user interaction.

Full protection features include hiccup current limiting, output over-voltage protection (OVP), and thermal shutdown.

The MP5408 requires a minimal number of readily available, standard, external components and is available in a QFN-26 (5mmx5mm) package.

### **FEATURES**

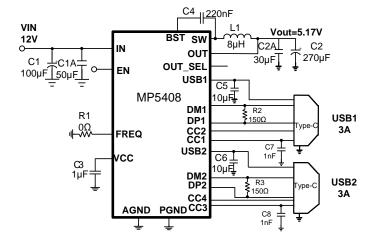
- Wide 6V to 36V Operating Input Voltage Range
- Selectable Output Voltage: 5.1V, 5.17V, and 5.3V
- 90mV Line Drop Compensation
- Accurate USB1/USB2 Output Current Limit
- 18mΩ/15mΩ Low R<sub>DS(ON)</sub> Internal Buck Power MOSFETs
- 13mΩ/13mΩ Low R<sub>DS(ON)</sub> Internal USB1/USB2 Power MOSFETs
- Frequency Adjustable (235kHz to 2.2MHz)
- Forced Continuous Conduction Mode (CCM) Operation
- Hiccup Current Limit for both Buck and USB
- Supports DCP Schemes for BC1.2, Divider Mode, and 1.2V/1.2V Mode
- Supports USB Type-C 5V @ 3A DFP Mode
- ±8kV HBM ESD Rating for USB, DP, and DM Pins
- Available in a QFN-26 (5mmx5mm) Package

### **APPLICATIONS**

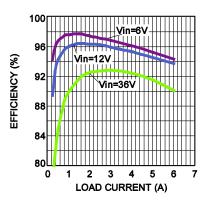
- USB Dedicated Charging Ports (DCP)
- USB Type-C 5V @ 3A DFP
- Automotive Cigarette Lighter Adapters
- Power Supply for Linear Chargers

All MPS parts are lead-free, halogen-free, and adhere to the RoHS directive. For MPS green status, please visit the MPS website under Quality Assurance. "MPS", the MPS logo, and "Simple, Easy Solutions" are trademarks of Monolithic Power Systems, Inc. or its subsidiaries.

# TYPICAL APPLICATION



### Efficiency vs. Load Current





# ORDERING INFORMATION

Part Number*	Package	Top Marking
MP5408GU	QFN-26 (5mmx5mm)	See Below

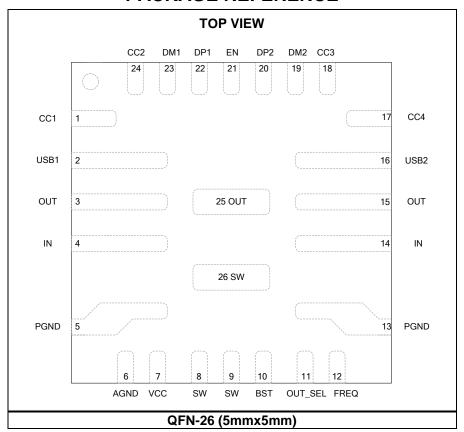
<sup>\*</sup> For Tape & Reel, add suffix -Z (e.g.: MP5408GU-Z).

# **TOP MARKING**

M<u>PSYYWW</u> MP5408 LLLLLL

MPS: MPS prefix YY: Year code WW: Week code MP5408: Part number LLLLLL: Lot number

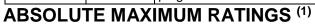
# **PACKAGE REFERENCE**





# **PIN FUNCTIONS**

QFN 5x5 Pin #	Name	Description
1	CC1	<b>Configuration channel.</b> CC1 is used to detect connections and configure the interface across the USB1 Type-C cables and connectors. Once a connection is established, CC1 or CC2 is reassigned to provide power over the V <sub>CONN</sub> pin of the plug.
2	USB1	USB1 output.
3, 15, 25	OUT	Buck output. OUT is the power input for USB1 and USB2.
4, 14	IN	<b>Supply voltage.</b> IN is the drain of the internal power device and provides power to the entire chip. The MP5408 operates from a 6V to 36V input voltage. The input capacitor $(C_{\text{IN}})$ prevents large voltage spikes at the input. Place $C_{\text{IN}}$ as close to the IC as possible.
5, 13	PGND	<b>Power ground.</b> PGND is the reference ground of the regulated output voltage. PGND requires extra care during the PCB layout. Connect PGND with copper traces and vias.
6	AGND	Analog ground. Connect AGND to PGND.
7	VCC	Internal 4.5V LDO regulator output. Decouple VCC with a 1µF capacitor.
8, 9, 26	SW	Switch output. Use a wide PCB trace to make the connection.
10	BST	<b>Bootstrap.</b> Connect a 0.22µF capacitor between SW and BST to form a floating supply across the high-side switch driver.
11	OUT_SEL	<b>Buck output voltage set.</b> By setting OUT_SEL to low, floating, or high, three different output voltages can be achieved: 5.1V, 5.17V, or 5.3V.
12	FREQ	<b>Switching frequency program input.</b> Connect a resistor from FREQ to GND to set the switching frequency. Float FREQ or connect FREQ to VCC for the default 450kHz frequency. Connect FREQ to ground for a 235kHz internal frequency.
16	USB2	USB2 output.
17	CC4	<b>Configuration channel.</b> CC4 is used to detect connections and configure the interface across the USB2 Type-C cables and connectors. Once a connection is established, CC3 or CC4 is reassigned to provide power over the $V_{\text{CONN}}$ pin of the plug.
18	CC3	<b>Configuration channel.</b> CC3 is used to detect connections and configure the interface across the USB2 Type-C cables and connectors. Once a connection is established, CC3 or CC4 is reassigned to provide power over the $V_{\text{CONN}}$ pin of the plug.
19	DM2	<b>D- data line to USB2 connector.</b> DM2 is the input/output used for handshaking with portable devices.
20	DP2	<b>D+</b> data line to USB2 connector. DP2 is the input/output used for handshaking with portable devices.
21	EN	On/off control input. EN has an internal auto pull-up with an 8µA current source.
22	DP1	<b>D+ data line to USB1 connector.</b> DP1 is the input/output used for handshaking with portable devices.
23	DM1	<b>D- data line to USB1 connector.</b> DM1 is the input/output used for handshaking with portable devices.
24	CC2	<b>Configuration channel.</b> CC2 is used to detect connections and configure the interface across the USB1 Type-C cables and connectors. Once a connection is established, CC1 or CC2 is reassigned to provide power over the V <sub>CONN</sub> pin of the plug.
	l	



V<sub>SW</sub>.....-0.3V (-5V for <10ns)

Supply voltage (V<sub>IN</sub>) ......40V





$V_{BST}$ $V_{SW}$ + 5.5 $V$
VEN0.3V to +10V (2)
$V_{\text{OUT}}, V_{\text{USB}}$ -0.3V to +6.5V
All other pins0.3V to +5.5V
Continuous power dissipation $(T_A = +25^{\circ}C)^{(3)}$
QFN-26 (5mmx5mm)6.25W
Junction temperature 150°C
Lead temperature260°C
Storage temperature65°C to +150°C
Recommended Operating Conditions (4)
Operation input voltage range 6V to 36V
Output current 3A (USB1), 3A (USB2)
Operating junction temp. (T <sub>J</sub> )40°C to +125°C

Thermal Resistance QFN-26 (5mmx5mm)	$oldsymbol{ heta}_{JA}$	$oldsymbol{ heta}_{JC}$	
JESD51-7 <sup>(5)</sup>	44	9	.°C/W
50mmx50mm 4-Layer PCB	20	2	.°C/W

### NOTES:

- Absolute maximum ratings are rated under room temperature unless otherwise noted. Exceeding these ratings may damage the device.
- For details on EN's ABS max rating, please refer to the EN Control section on page 11.
- 3) The maximum allowable power dissipation is a function of the maximum junction temperature  $T_J$  (MAX), the junction-to-ambient thermal resistance  $\theta_{JA}$ , and the ambient temperature  $T_A$ . The maximum allowable continuous power dissipation at any ambient temperature is calculated by  $P_D$  (MAX) =  $(T_J (MAX)-T_A)/\theta_{JA}$ . Exceeding the maximum allowable power dissipation produces an excessive die temperature, causing the regulator to go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage. Measured on a 4-layer PCB (50mmx50mm).
- The device is not guaranteed to function outside of its operating conditions.
- 5) Measured on JESD51-7 and 4-layer PCB.



# **ELECTRICAL CHARACTERISTICS**

 $V_{IN}$  = 12V,  $V_{EN}$  = 5V, CC1 = CC3 = 5.1k $\Omega$ ,  $T_J$  = -40°C to +125°C  $^{(6)}$ , typical value is tested at  $T_J$  = +25°C, unless otherwise noted.

Parameter	Symbol	Condition	Min	Тур	Max	Units	
Supply current (shutdown)	I <sub>IN</sub>	V <sub>EN</sub> = 0V		13	18	μΑ	
	I <sub>Q1</sub>	No switching		1	2	mA	
Supply current (quiescent)	I <sub>Q2</sub>	CC floating, V <sub>BUS</sub> disabled, T <sub>J</sub> = +25°C		200	300	μA	
EN rising threshold	V <sub>EN_Rising</sub>		-3%	1.235	+3%	V	
EN hysteresis	$V_{EN\_HYS}$			200		mV	
EN pull-up current	I <sub>EN</sub>		4	8	12	μΑ	
Thermal shutdown (7)	T <sub>TSD</sub>			165		°C	
Thermal hysteresis (7)	T <sub>TSD_HYS</sub>			20		°C	
VCC regulator	Vcc		4.2	4.5	4.85	V	
VCC load regulation	Vcc_log	Icc = 50mA		1	3	%	
Step-Down Converter							
V <sub>IN</sub> under-voltage lockout threshold rising	VIN_UVLO		4.6	5	5.4	V	
V <sub>IN</sub> under-voltage lockout threshold hysteresis	V <sub>UVLO_HYS</sub>			700		mV	
HS switch on resistance	R <sub>DSON_HS</sub>			18		mΩ	
LS switch on resistance	R <sub>DSON_LS</sub>			15		mΩ	
		OUT_SEL = low, T <sub>J</sub> = +25°C	-1.5%	5.1	+1.5%		
		$OUT\_SEL = float, T_J = +25$ °C	-1%	5.17	+1%		
Output voltage	Vouт	OUT_SEL = float, $T_J = -40$ °C to +125°C	-2%	5.17	+2%	V	
		$OUT_SEL = high, T_J = +25$ °C	-1.5%	5.3	+1.5%		
Output over-voltage protection (OVP)	$V_{OVP\_R}$		5.45	5.85	6.25	V	
Output OVP recovery	$V_{OVP\_F}$		5.3	5.7	6.1	V	
Output to ground resistance	RDischarge			175		kΩ	
Low-side current limit	I <sub>LS_LIMIT</sub>			-2		Α	
Cuitali Inglia	CVA/	$V_{EN} = 0V$ , $V_{SW} = 36V$ or $0V$ , $T_{J} = +25$ °C	/ <sub>SW</sub> = 36V or 0V,	1			
Switch leakage	SW <sub>LKG</sub>	$V_{EN} = 0V$ , $V_{SW} = 36V$ or $0V$ , $T_{J} = -40^{\circ}C$ to $+125^{\circ}C$			5	μA	
High-side current limit	I <sub>LIMIT</sub>	40% duty cycle	9	13		Α	
	F <sub>SW1</sub>	Pull R <sub>FREQ</sub> to GND		235			
Oscillator fraguesco	F <sub>SW2</sub>	$R_{FREQ} = 66.5k\Omega$		350		kHz	
Oscillator frequency	F <sub>SW3</sub>	$R_{FREQ} = 9.53k\Omega$		2200			
	F <sub>SW4</sub>	R <sub>FREQ</sub> = float	350	450	530		
Maximum duty cycle	D <sub>MAX</sub>	FREQ = 450kHz		95		%	



ELECTRICAL CHARACTERISTICS (continued)  $V_{IN} = 12V$ ,  $V_{EN} = 5V$ , CC1 = CC3 =  $5.1k\Omega$ ,  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$  (6), typical value is tested at  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$  (9), typical value is tested at  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$  (9), typical value is tested at  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$  (10), typical value is tested at  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$  (10), typical value is tested at  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$  (10), typical value is tested at  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$  (10), typical value is tested at  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$  (10), typical value is tested at  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$  (10), typical value is tested at  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$  (10), typical value is tested at  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$  (10), typical value is tested at  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$  (10), typical value is tested at  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$  (10), typical value is tested at  $T_J = -40^{\circ}C$ +25°C, unless otherwise noted.

Parameter	Symbol	Condition	Min	Тур	Max	Units
Minimum off time	T <sub>OFF_MIN</sub>			110		ns
Minimum on time (7)	T <sub>ON_MIN</sub>			130		ns
Soft-start time	Tss	Output from 10% to 90%, $T_J = +25$ °C		2		ms
USB Switch (USB1 and US	SB2)					
Under-voltage lockout threshold rising	Vusb_uvr		3.7	4	4.3	V
Under-voltage lockout threshold hysteresis	Vusb_uvhys			200		mV
Switch on resistance	R <sub>DSON_SW</sub>			13		mΩ
Output discharge resistance	Rdis_usb	Apply a 5V voltage on the USB output, float CC pin		500		kΩ
USB OVP clamp	V <sub>USB_OV</sub>		5.3	5.6	5.9	V
Current limit	ILimit1	V <sub>OUT</sub> drops 10% , Type-C mode	3.1	3.45	3.8	
Current IIIIII	I <sub>Limit2</sub>	$T_J = +25$ °C , $V_{OUT}$ drops 10%, Type-A mode	2.6	2.75	2.9	Α
Line drop compensation	VDROP_COM	I <sub>OUT</sub> = 2.4A , V <sub>OUT</sub> = 5V, T <sub>J</sub> = +25°C		90		mV
V <sub>BUS</sub> soft-start time	Tss	Output from 10% to 90%	1	2	3	ms
I licerum manda on timo	_	OC, Vouт drops 10%, T <sub>J</sub> = +25°C	, T <sub>J</sub> = 3.5		6.5	
Hiccup mode on time	THICP_ON2	OC, V <sub>OUT</sub> drops 10%, T <sub>J</sub> = - 40°C to +125°C	3	5	7	7 ms
Hiccup mode off time	T <sub>HICP_OFF</sub>	Vout connected to GND		2		S
BC1.2 DCP Mode	•					
DP and DM short	D	V <sub>DP</sub> = 0.8V, I <sub>DM</sub> = 1mA, T <sub>J</sub> = +25°C		85	155	Ω
resistance	R <sub>DP/DM_Short</sub>	$V_{DP} = 0.8V$ , $I_{DM} = 1mA$ , $T_{J} = -40$ °C to $+125$ °C		85	160	12
Divider Mode						
DP/DM output voltage	V <sub>DP/DM_Divider</sub>		2.55	2.7	2.85	V
DP/DM output impedance	R <sub>DP/DM_Divider</sub>	T <sub>J</sub> = +25°C	14	22	30	kΩ
	TOF/DIVI_DIVIQE	$T_J = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	12	22	34	1/22
1.2V/1.2V Mode	1	,		1	1	T
		$V_{OUT} = 5V, T_J = +25^{\circ}C$	1.12	1.2	1.28	, ,
DP/DM output voltage	VDP/DM_1.2V	$V_{OUT} = 5V$ , $T_J = -40^{\circ}C$ to $+125^{\circ}C$	1.1	1.2	1.3	V
DP/DM output impedance	R <sub>DP/DM_1.2V</sub>	T <sub>J</sub> = +25°C	70	105	140	kΩ
Di /Divi output iiripedance	1.2V	$T_{J} = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	60	105	150	K\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\



+25°C, unless otherwise noted.

Parameter	Symbol	mbol Condition		Тур	Max	Units	
USB Type-C 5V @ 3A Mod	USB Type-C 5V @ 3A Mode – CC1, CC2, CC3, and CC4						
CC resistor to disable Type-C mode	R <sub>A</sub>	CC1 and CC3	70		90	kΩ	
CC voltage to enable VCONN	$V_{Ra}$				0.75	V	
CC voltage to enable V <sub>BUS</sub>	$V_{Rd}$		0.9		2.45	V	
CC detach threshold	$V_{Detach}$		2.75				
CC voltage falling debounce timer	$T_{CC\_debounce}$	V <sub>BUS</sub> enable deglitch	100	144	200	ms	
CC voltage rising debounce timer	T <sub>PD_debounce</sub>	V <sub>BUS</sub> disable deglitch	10	15	20	ms	
VCONN output power	Pvconn	V <sub>CONN</sub> comes from the buck output with some series resistance, T <sub>J</sub> = +25°C	1			W	

### NOTES:

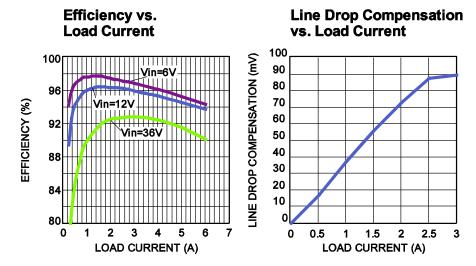
<sup>6)</sup> All min/max parameters are tested at T<sub>J</sub> = 25°C. Limits over temperature are guaranteed by design, characterization, and correlation.

<sup>7)</sup> Guaranteed by design and characterization test.



# TYPICAL PERFORMANCE CHARACTERISTICS

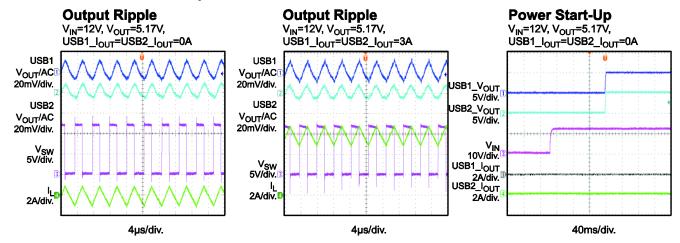
 $V_{IN}$  = 12V,  $V_{OUT}$  = 5.17V, L = 8 $\mu$ H,  $T_A$  = 25°C, unless otherwise noted.

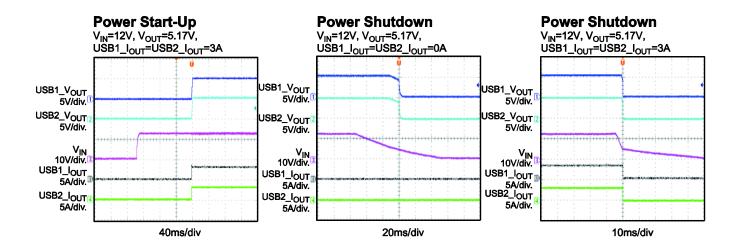




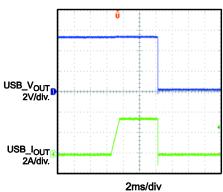
# TYPICAL PERFORMANCE CHARACTERISTICS (continued)

 $V_{IN} = 12V$ ,  $V_{OUT} = 5.17V$ ,  $L = 8\mu H$ ,  $T_A = 25$ °C, unless otherwise noted.



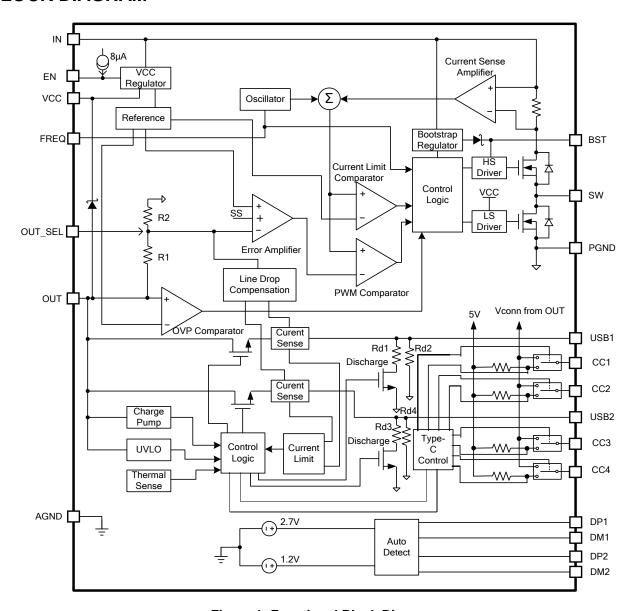








# **BLOCK DIAGRAM**



**Figure 1: Functional Block Diagram** 

© 2018 MPS. All Rights Reserved.



# OPERATION BUCK CONVERTER SECTION

MP5408 integrates monolithic. а synchronous, rectified, step-down, switch-mode converter with internal power MOSFETs and two USB current-limit switches with chargingport auto-detection. The MP5408 offers a achieves compact solution that 6A continuous output current with excellent load and line regulation over a wide input supply range.

The MP5408 operates in a fixed-frequency, peak-current-mode control to regulate the output voltage. The internal clock initiates the pulse-width modulation (PWM) cycle, which turns on the integrated high-side power MOSFET (HS-FET). The HS-FET remains on until its current reaches the value set by the COMP voltage ( $V_{\text{COMP}}$ ). When the power switch is off, it remains off until the next clock cycle begins. If the duty cycle reaches 95% (450kHz switching frequency) in one PWM period, the current in the power MOSFET does not reach the COMP-set current value, and the power MOSFET turns off.

### **Error Amplifier (EA)**

The error amplifier (EA) compares the internal feedback voltage against the internal reference (REF) and outputs  $V_{\text{COMP}}$ .  $V_{\text{COMP}}$  controls the power MOSFET current. The optimized, internal compensation network minimizes the external component count and simplifies the control loop design.

### **Internal VCC Regulator**

The 4.5V internal regulator powers most of the internal circuitries. This regulator takes  $V_{\text{IN}}$  and operates in the full  $V_{\text{IN}}$  range. When  $V_{\text{IN}}$  exceeds 4.5V, the output of the regulator is in full regulation. If  $V_{\text{IN}}$  is less than 4.5V, the output decreases with  $V_{\text{IN}}$ . VCC requires an external 1µF ceramic decoupling capacitor.

After the buck output starts up, the internal VCC LDO output is biased by the buck output through a Schottky diode.

### **Enable (EN) Control**

The MP5408 has an enable (EN) control pin. An internal 8µA pull-up current allows EN to be floated for automatic start-up. Pull EN high or float EN to enable the IC. Pull EN low to disable the IC.

EN is clamped internally using a 7.6V series Zener diode and a 10V breakdown voltage of the ESD cell (see Figure 2).

Connect EN through a pull-up resistor to  $V_{\text{IN}}$  to enhance the EN pull-up current ability. This requires limiting the EN voltage below 10V or limiting the EN input current below 500 $\mu$ A if the EN pull-up voltage is larger than 10V.

For example, if connecting EN to  $V_{IN}=36V$ , then  $R_{PULLUP} \ge (36V-10V)/500\mu A=52k\Omega$ .

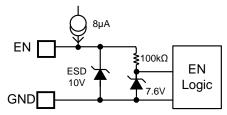


Figure 2: Zener Diode between EN and GND

## Setting the Switching Frequency

Connect a resistor from FREQ to ground to set the switching frequency (see Table 1). The value of the frequency can be calculated approximately with Equation (1):

FREQ(kHz) = 
$$\frac{1000000}{42.5 \times R_{FREQ}(K\Omega) + 53.7}$$
 (1)

The frequency vs. R<sub>FREQ</sub> is shown in Figure 3.

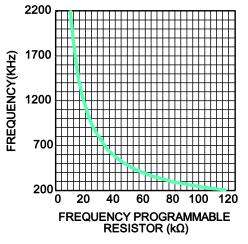


Figure 3: Switching Frequency vs. RFREQ

© 2018 MPS. All Rights Reserved.



Table 1: Recommended Resistor Values for Typical Switching Frequency

R <sub>FREQ</sub> (kΩ)	F <sub>S</sub> (kHz)
0	235
66.5	350
NS	450
45.8	500
22.3	1000
14.6	1500
9.53	2200

Two internal comparators monitor FREQ's logic voltage to enable FREQ to float or short to GND. During power-up, there is another internal source current on FREQ. The frequency is locked at 450kHz when a voltage greater than 2V and a current greater than 8µs is sensed on FREQ. The frequency is locked at 235kHz when a voltage less than 0.1V and a current greater than 8µs is sensed on FREQ. Leave FREQ floating or connect FREQ to VCC to achieve 450kHz default switching the frequency. Short FREQ to ground to achieve a 235kHz frequency (see Figure 4).

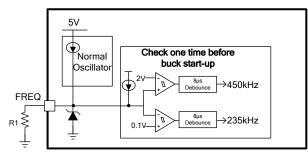


Figure 4: Switching Frequency Functional Block Under-Voltage Lockout (UVLO)

Under-voltage lockout (UVLO) protects the chip from operating at an insufficient supply voltage. The UVLO comparator monitors the input voltage. The UVLO rising threshold is 5V, and its falling threshold is 4.3V.

### Internal Soft Start (SS)

Soft start (SS) prevents the converter output voltage from overshooting during start-up. When the chip starts up, the internal circuitry generates a SS voltage that ramps up from 0V to 5V. When SS is lower than REF, the error amplifier uses SS as the reference. When SS is higher than REF, the error amplifier uses REF as the reference. The SS time is set to 2ms internally. If the output of the MP5408 is pre-biased to a certain voltage during start-up, the

IC disables the switching of both the high-side and low-side switches until the voltage on the internal SS capacitor exceeds the internal feedback voltage.

### **Forced CCM Operation**

The MP5408 works in forced continuous conduction mode (CCM) continuously. The MP5408 operates in a fixed switching frequency regardless of whether it is operating in light load or full load. The advantage of CCM is the controllable frequency, smaller output ripple, and sufficient bootstrap charge time, but it also has low efficiency at light-load condition. A proper inductance should be selected to avoid triggering the low-side switch's negative current limit (typically 2A, from SW to GND). If the negative current limit is triggered, the low-side switch turns off, and the high-side switch turns on when the internal clock comes around.

### **Buck Over-Current Protection (OCP)**

The MP5408 has a cycle-by-cycle over-current limit when the inductor peak current exceeds the current-limit threshold, and the FB voltage drops below the under-voltage (UV) threshold (typically 50% below the reference). Once UV is triggered, the MP5408 enters hiccup mode to restart the part periodically. This protection mode is especially useful when the output is dead-shorted to ground. This reduces the average short-circuit current greatly, alleviates thermal issues, and protects the regulator. The MP5408 exits hiccup mode once the overcurrent condition is removed.

### **Buck Output Over-Voltage Protection (OVP)**

The MP5408 has output over-voltage protection (OVP). If the output is higher than 5.85V, the high-side switch stops turning on. The low-side switch turns on to discharge the output voltage until the output decreases to 5.7V, and then the chip resumes normal operation.

### Floating Driver and Bootstrap Charging

An external bootstrap capacitor powers the floating power MOSFET driver. This floating driver has its own UVLO protection. The UVLO's rising threshold is 2.2V with a hysteresis of 150mV. The bootstrap capacitor voltage is regulated internally by V<sub>IN</sub> and VCC through D1, D2, M1, C4, L1, and C2 (see Figure 5). The BST capacitor (C4) voltage is



charged up quickly by VCC through M1. The 2.5µA input to the BST current source can also charge the BST capacitor when the low-side switch does not turn on.

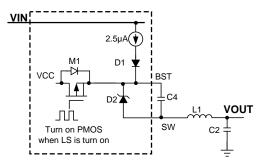


Figure 5: Internal Bootstrap Charging Circuit

### Start-Up and Shutdown

If both IN and EN exceed their respective thresholds, the chip is enabled. The reference block starts first, generating a stable reference voltage and current, and then the internal regulator is enabled. The regulator provides a stable supply for the remaining circuitries.

Three events can shut down the chip: EN low, IN low, and thermal shutdown. During shutdown, the signaling path is first blocked to avoid any fault triggering. Then  $V_{\text{COMP}}$  and the internal supply rail are pulled down. The floating driver is not subject to this shutdown command.

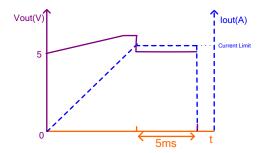
### **Buck Output Impedance**

The buck does not involve an output discharge function during the EN shutdown. After the EN shutdown, there are only two feedback resistors connected to OUT, which has a total typical resistance of  $175k\Omega$ .

# USB CURRENT-LIMIT SWITCH SECTION Over-Current Protection (OCP) and Hiccup

The MP5408 integrates two USB current-limit switches. The MP5408 provides built-in soft-start circuitry that controls the rising slew rate of the output voltage to limit inrush current and voltage surges.

When the load current reaches the current-limit threshold, the USB power MOSFET works in constant current-limit mode (see Figure 6). If the over-current limit condition lasts longer than 5ms ( $V_{\text{OUT}}$  does not drop too low), the corresponding USB channel enters hiccup mode with 5ms of on time and 2s of off time. Another USB channel works normally.



**Figure 6: Over-Current Limit** 

After the soft start finishes, if the USB output voltage is lower than 3.5V and lasts longer than 50µs, the MP5408 enters hiccup without having to wait 5ms (see Figure 7). This can prevent abnormal thermal rise during the constant resistor (CR) load over-current case.

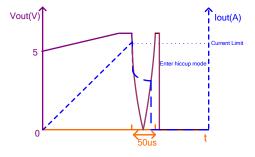


Figure 7: Over-Current Limit for CR Load

# Fast Response for Short-Circuit Protection (SCP)

If the load current increases rapidly due to a short-circuit event, the current may exceed the current limit threshold before the control loop is able to respond. If the current reaches the 7A secondary current limit level, a fast turn-off circuit activates to turn off the power MOSFET. This can help limit the peak current through the switch, keeping the buck output voltage from dropping too much and affecting another USB channel. The total short-circuit response time is less than 1µs.

When the fast turn-off function is triggered, the MOSFET turns off for 100µs and restarts with a soft start. During the restart process, if the short still remains, the MP5408 regulates the gate voltage to hold the current at a normal current-limit level.



### **Output Line Drop Compensation**

The MP5408 can compensate for an output voltage drop, such as high impedance caused by a long trace, to maintain a fairly constant output voltage at the load-side voltage.

The internal comparator compares the currentsense output voltage of the two current-limit switches and uses the larger current-sense output voltage to compensate for the line drop voltage. The line drop compensation amplitude increases linearly as the load current increases and also has an upper limitation. The line drop compensation at a 3A output current is 90mV.

### **USB Output Over-Voltage Clamp**

To protect the device at the cable terminal, the USB switch output has a fixed over-voltage protection (OVP) threshold. When the input voltage is higher than the OVP threshold, the output voltage is clamped at 5.6V.

### **USB Output Discharge and Impedance**

Each USB switch has a fast discharge path that can discharge the external output capacitor's energy quickly during a power shutdown. This function is active when the CC pins are released or the part is disabled (input voltage is under UVLO or EN off). The discharge path is turned off when the USB output voltage is discharged below 50mV. After the fast discharge path turns off, there is only a high impedance resistor (typically 500k $\Omega$ ) from USB1 or USB2 to ground.

## **Auto-Detection**

The MP5408 integrates a USB-dedicated charging port auto-detect function. This function recognizes most mainstream portable devices and supports the following charging schemes:

- USB battery charging specification BC1.2/ Chinese Telecommunications Industry standard YD/T 1591-2009
- Apple divider mode
- 1.2V/1.2V mode
- USB Type-C 5V @ 3A DFP mode

The auto-detect function is a state machine that supports all of the DCP charging schemes above. Connect DP and DM with a  $150\Omega$  resistor for DCP mode.

### **USB Type-C Mode and V<sub>CONN</sub>**

For USB Type-C solutions, two pins (CC1 and CC2) on the connector are used to establish and manage the source-to-sink connection. The general concept for setting up a valid connection between a source and a sink is based on being able to detect terminations residing in the product being attached. To aid in defining the functional behavior of CC, a pull-up (Rp) and pull-down (Rd  $5.1k\Omega$ ) termination model is used based on a pull-up resistor and pull-down resistor (see Figure 8).

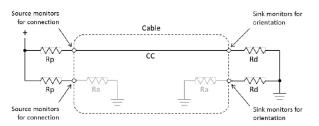


Figure 8: Current Source/Pull-Down CC Model

Initially, a source exposes independent Rp terminations on its CC1 and CC2 pins, and a sink exposes independent Rd terminations on its CC1 and CC2 pins. The source-to-sink combination of this circuit configuration represents a valid connection. To detect this, the source monitors CC1 and CC2 for a voltage lower than its unterminated voltage. Choosing Rp is a function of the pull-up termination voltage and the source's detection circuit. This indicates that either a sink, a powered cable, or a sink connected via a powered cable has been attached. Prior to the application of V<sub>CONN</sub>, a powered cable exposes Ra (typically  $1k\Omega$ ) on its V<sub>CONN</sub> pin. Ra represents the load on V<sub>CONN</sub> plus any resistive elements to ground. In some cable plugs, this might be a pure resistance, and in others, it may simply be the load.

The source must be able to differentiate between the presence of Rd and Ra to know whether there is a sink attached and where to apply  $V_{\text{CONN}}$ . The source is not required to source  $V_{\text{CONN}}$  unless Ra is detected.

Two special termination combinations on the CC pins as seen by a source are defined for directly attached accessory modes: Ra/Ra for audio adapter accessory mode and Rd/Rd for debug accessory mode (see Figure 9, Table 2).

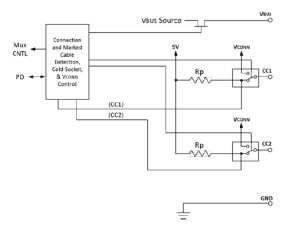


Figure 9: CC Functional Block

A port that behaves as a source has the following functional characteristics.

- 1. The source uses a MOSFET to enable or disable the power delivery across  $V_{\text{BUS}}$ . Initially, the source is disabled.
- 2. The source supplies pull-up resistors (Rp) on CC1 and CC2 and monitors both to detect a sink. The presence of an Rd pull-down resistor on CC1 or CC2 indicates that a sink is being attached. The value of Rp indicates the initial USB Type-C current level supported by the host. The MP5408's Rp is  $10k\Omega$ , which represents a 3A current level.
- The source uses the CC pull-down characteristic to detect and determine which CC pin is intended to supply V<sub>CONN</sub> (when Ra is discovered).
- 4. Once a sink is detected, the source enables V<sub>BUS</sub> and V<sub>CONN</sub>.
- 5. The source monitors the continued presence of Rd to detect a sink detach. When a detach event is detected, the source is removed, and  $V_{\text{BUS}}$  and  $V_{\text{CONN}}$  return to step 2.

### Disable Type-C Mode (Type-A Mode)

During the MP5408 initial start-up, the IC sources  $10\mu\text{A}$  for  $20\mu\text{s}$  on CC1. If the CC1 voltage falls into a 400mV to 1.2V voltage range, USB1 latches in Type-A mode unless the part is re-enabled. Type-C mode is disabled, so CC is attached, the detach logic is disabled, and  $\text{V}_{\text{BUS}}$  is always enabled. The current limit changes to a Type-A spec. The same logic is implemented on CC3 for USB2.

To trigger Type-A mode, the external pull-down resistor should be 70 -  $90k\Omega$ . Do not connect extra capacitors on CC1 and CC3.

In normal Type-C mode applications, a 1nF capacitor should be added on CC1 and CC3 to avoid triggering Type-A mode falsely. Refer to the typical schematic for detail.

The MP5408 also supports debug mode and audio adapter accessory mode in Type-C applications. If two Ra resistors pull down CC1 and CC2, or two Rd resistors pull down CC1 and CC2, there is no action inside the IC ( $V_{BUS}$  is not enabled).

### **Thermal Shutdown**

Thermal shutdown prevents the chip from operating at exceedingly high temperatures. When the silicon die temperature exceeds 165°C, the entire chip shuts down. When the temperature falls below its lower threshold (typically 145°C), the chip is enabled.



# **Table 2: CC Logic Truth Table**

EN	CC of USB1 (8)	CC of USB2 (8)	Buck	V <sub>CONN</sub> (USB1)	USB1	V <sub>CONN</sub> (USB2)	USB2
0	X	X	Disabled	Disabled	Disabled	Disabled	Disabled
	AUDIO		Disabled	Disabled	Disabled	Disabled	Disabled
	DEBUG	On an ar ALIDIO	Disabled	Disabled	Disabled	Disabled	Disabled
1	"A" <sup>(9)</sup>	Open or AUDIO or DEBUG	Enabled	Disabled	Enabled	Disabled	Disabled
	Rd, Ra	OI DEBOG	Enabled	Enabled	Enabled	Disabled	Disabled
	Open		Disabled	Disabled	Disabled	Disabled	Disabled
	AUDIO	Rd, Ra	Enabled	Disabled	Disabled	Enabled	Enabled
	DEBUG		Enabled	Disabled	Disabled	Enabled	Enabled
1	"A"		Enabled	Disabled	Enabled	Enabled	Enabled
	Rd, Ra		Enabled	Enabled	Enabled	Enabled	Enabled
	Open		Enabled	Disabled	Disabled	Enabled	Enabled
	AUDIO		Enabled	Disabled	Disabled	Disabled	Enabled
1	DEBUG		Enabled	Disabled	Disabled	Disabled	Enabled
	"A"	"A"	Enabled	Disabled	Enabled	Disabled	Enabled
	Rd, Ra		Enabled	Enabled	Enabled	Disabled	Enabled
	Open		Enabled	Disabled	Disabled	Disabled	Enabled

- USB1 and USB2 are symmetric to each other.
- "A" means Type-A mode. CC1 (CC3 for USB2) is requested to be pulled down by an 80.6kΩ resistor to enter this mode.



### APPLICATION INFORMATION

### Selecting the Inductor

For most applications, use an inductor with a DC current rating at least 25% higher than the maximum load current. Select an inductor with a small DC resistance for optimum efficiency. For most designs, the inductor value can be calculated with Equation (2):

$$L_{1} = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{V_{IN} \times \Delta I_{L} \times f_{OSC}}$$
(2)

Where  $\Delta I_L$  is the inductor ripple current.

Choose the inductor ripple current to be approximately 30% of the maximum load current. The maximum inductor peak current can be calculated with Equation (3):

$$I_{L(MAX)} = I_{LOAD} + \frac{\Delta I_{L}}{2}$$
 (3)

### **Selecting the Buck Input Capacitor**

The input current to the step-down converter is discontinuous and therefore requires AC capacitor vlagus current maintaining the DC input voltage. Use low ESR capacitors for optimum performance. Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of their low ESR and small temperature coefficients. 100µF electrolytic and 50µF ceramic capacitors are recommended in applications with a 235kHz switching frequency.

Since the input capacitor (C1) absorbs the input switching current, it requires an adequate ripple current rating. The RMS current in the input capacitor can be estimated with Equation (4):

$$I_{C1} = I_{LOAD} \times \sqrt{\frac{V_{OUT}}{V_{IN}}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right)$$
(4)

The worst-case condition occurs at  $V_{IN} = 2V_{OUT}$ , shown in Equation (5):

$$I_{C1} = \frac{I_{LOAD}}{2} \tag{5}$$

For simplification, choose an input capacitor with an RMS current rating greater than half of the maximum load current.

The input capacitor can be electrolytic, tantalum, or ceramic. When using an electrolytic capacitor, place two additional high-quality ceramic capacitors as close to IN as possible. Estimate the input voltage ripple caused by the capacitance with Equation (5):

$$\Delta V_{IN} = \frac{I_{LOAD}}{f_{s} \times C1} \times \frac{V_{OUT}}{V_{IN}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right)$$
 (5)

# **Selecting the Buck Output Capacitor**

The device requires an output capacitor (C2) to maintain the DC output voltage. Estimate the output voltage ripple with Equation (6):

$$\Delta V_{\text{OUT}} = \frac{V_{\text{OUT}}}{f_{\text{S}} \times L_{\text{1}}} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right) \times \left(R_{\text{ESR}} + \frac{1}{8 \times f_{\text{S}} \times C2}\right)$$
(6)

Where  $L_1$  is the inductor value, and RESR is the equivalent series resistance (ESR) value of the output capacitor.

For an electrolytic capacitor, the ESR dominates the impedance at the switching frequency. For simplification, the output ripple can be approximated with Equation (7):

$$\Delta V_{\text{OUT}} = \frac{V_{\text{OUT}}}{f_{\text{S}} \times L_{1}} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right) \times R_{\text{ESR}}$$
 (7)

A 100 - 270 $\mu$ F capacitor with an ESR less than  $50m\Omega$  (e.g.: polymer capacitor or tantalum capacitor) and three  $10\mu$ F ceramic capacitors are recommended in the application.

For CLA applications, set the switching frequency to be 235kHz for better thermal performance (see Table 3).

**Table 3: Recommended External Components** 

Switching Frequency	Inductor	Input Cap	Buck Output Capacitor
235kHz	8µН	50µF ceramic cap + 100µF E- cap	30μF ceramic cap + 270μF polymer cap
450kHz	4.7µH	50µF ceramic cap + 100µF E- cap	30μF ceramic cap + 270μF polymer cap



### **ESD Protection for I/O Pins**

Higher ESD levels should be considered for all USB I/O pins. The MP5408 features high ESD protection up to ±8kV human body model on DP, DM, USB1, and USB2, and ±5.5kV human body model on CC1 through CC4. The ESD structures can withstand high ESD in normal operation and when the device is powered off. To further extend DP and DM's ESD level for covering complicated application environments, additional resistors and capacitors can be added (see Figure 10).

Similar R-C networks cannot be added on CC1 or CC2 because the CC line must support 200mA of current and 300kHz of signaling. Additional ESD diodes can be added on the CC pins.

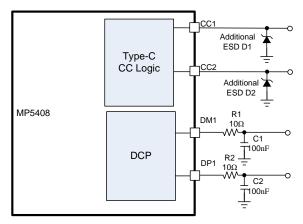


Figure 10: Recommended I/O Pins ESD Enhancing

### PCB Layout Guidelines (10)

Efficient PCB layout is critical for stable operation and thermal dissipation. For best results, refer to Figure 11 and follow the guidelines below.

- Connect OUT with short, direct, and wide traces.
- 2. Add vias under the IC.
- 3. Route the OUT trace on both PCB layers.
- 4. Place the buck output ceramic capacitor C2A and C2B on one side and C2C on the other side.
- 5. Add a large copper plane for PGND.
- 6. Add multiple vias to improve thermal dissipation.
- 7. Connect AGND to PGND.
- 8. Place a large copper plane for SW, USB, and USB2.
- Route the USB1 and USB2 traces on both PCB layers.
- 10. Add multiple vias.
- 11. Place two ceramic input decoupling capacitors as close to IN and PGND as possible to improve EMI performance.
- 12. Place the VCC decoupling capacitor as close to VCC as possible.

### NOTE:

 The recommended layout is based on the Typical Application Circuits in Figure 12 through Figure 14.

© 2018 MPS. All Rights Reserved.



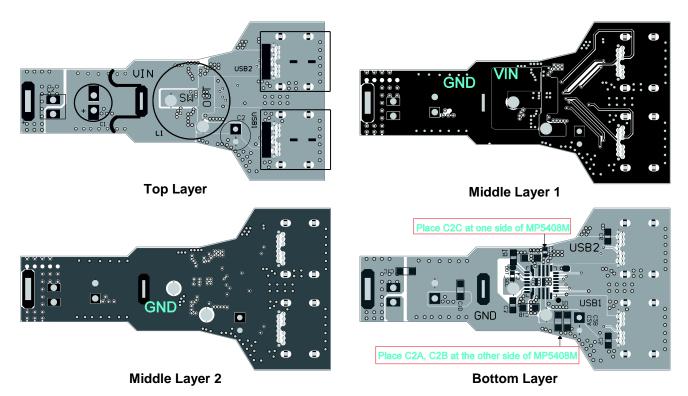


Figure 11: Recommended Layout



# TYPICAL APPLICATION CIRCUITS

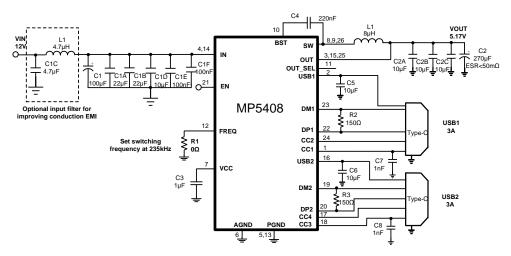


Figure 12: Dual USB Type-C 5V/3A DFP Ports (11)

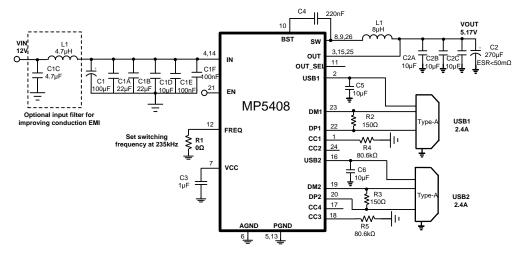


Figure 13: Dual USB Type-A 5V/2.4A Ports (11)

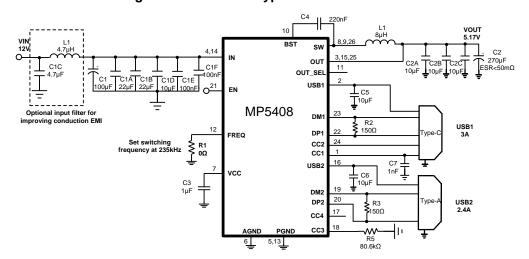


Figure 14: One Type-C 5V/3A DFP Port, One Type-A 5V/2.4A Port (11)

© 2018 MPS. All Rights Reserved.

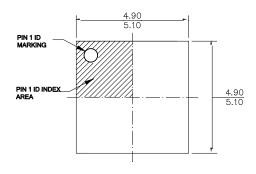
### NOTE:

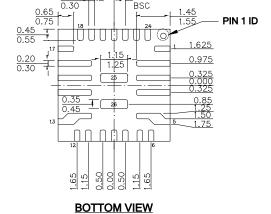
11) See Figure 10 for details on the I/O pins' ESD protection enhancement.



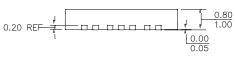
# **PACKAGE INFORMATION**

# QFN-26 (5mmx5mm)

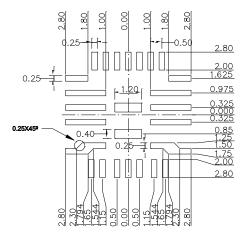




**TOP VIEW** 



SIDE VIEW



RECOMMENDED LAND PATTERN

### NOTE:

- 1) LAND PATTERNS OF PIN 2"4 AND 14"16 HAVE THE SAME LENGTH AND WIDTH.
- 2) LAND PATTERNS OF PIN 5 AND PIN13 HAVE THE SAME LENGTH AND WIDTH.
- 3) ALL DIMENSIONS ARE IN MILLIMETERS.
- 4) LEAD COPLANARITY SHALL BE 0.10 MILLIMETERS MAX.
- 5) REFERENCEIS MO-220.
- 6) DRAWING IS NOT TO SCALE.

**NOTICE:** The information in this document is subject to change without notice. Please contact MPS for current specifications. Users should warrant and guarantee that third party Intellectual Property rights are not infringed upon when integrating MPS products into any application. MPS will not assume any legal responsibility for any said applications.



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

### Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов:
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001:
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



### Как с нами связаться

**Телефон:** 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина,

дом 2, корпус 4, литера А.